

MODEL: HSS11-B20-P38 | **DESCRIPTION:** HEAT SINK

FEATURES

- TO-220 package
- solder pin
- aluminum alloy
- black anodized finish



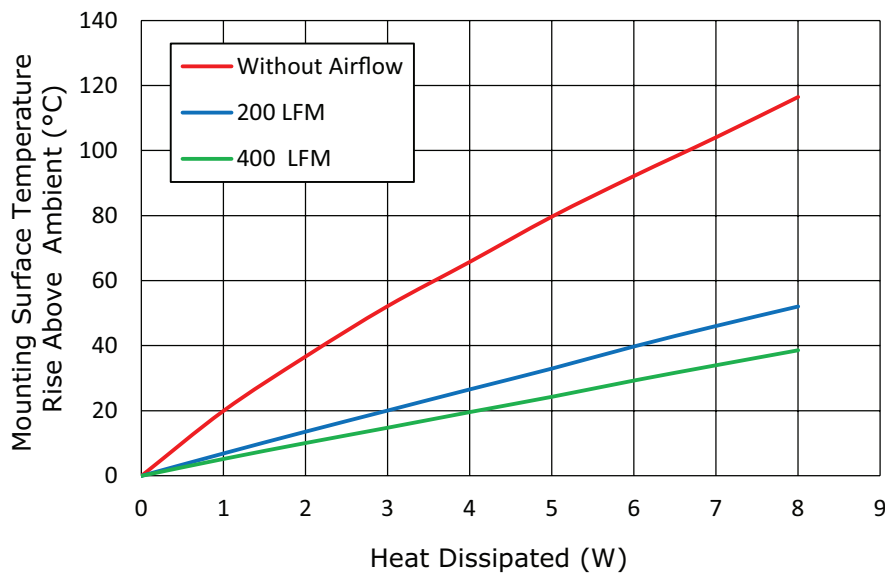
MODEL

HSS11-B20-P38	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	@ 75°C ΔT, nat conv [W]
	15.76	20.0	6.9	5.2	4.76

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	20.0	6.9	5.2
2	36.7	13.6	10.1
3	52.2	20.1	14.8
4	65.8	26.6	19.6
5	79.7	33.0	24.3
6	92.2	39.8	29.3
7	104.1	46.1	34.0
8	116.5	52.1	38.6

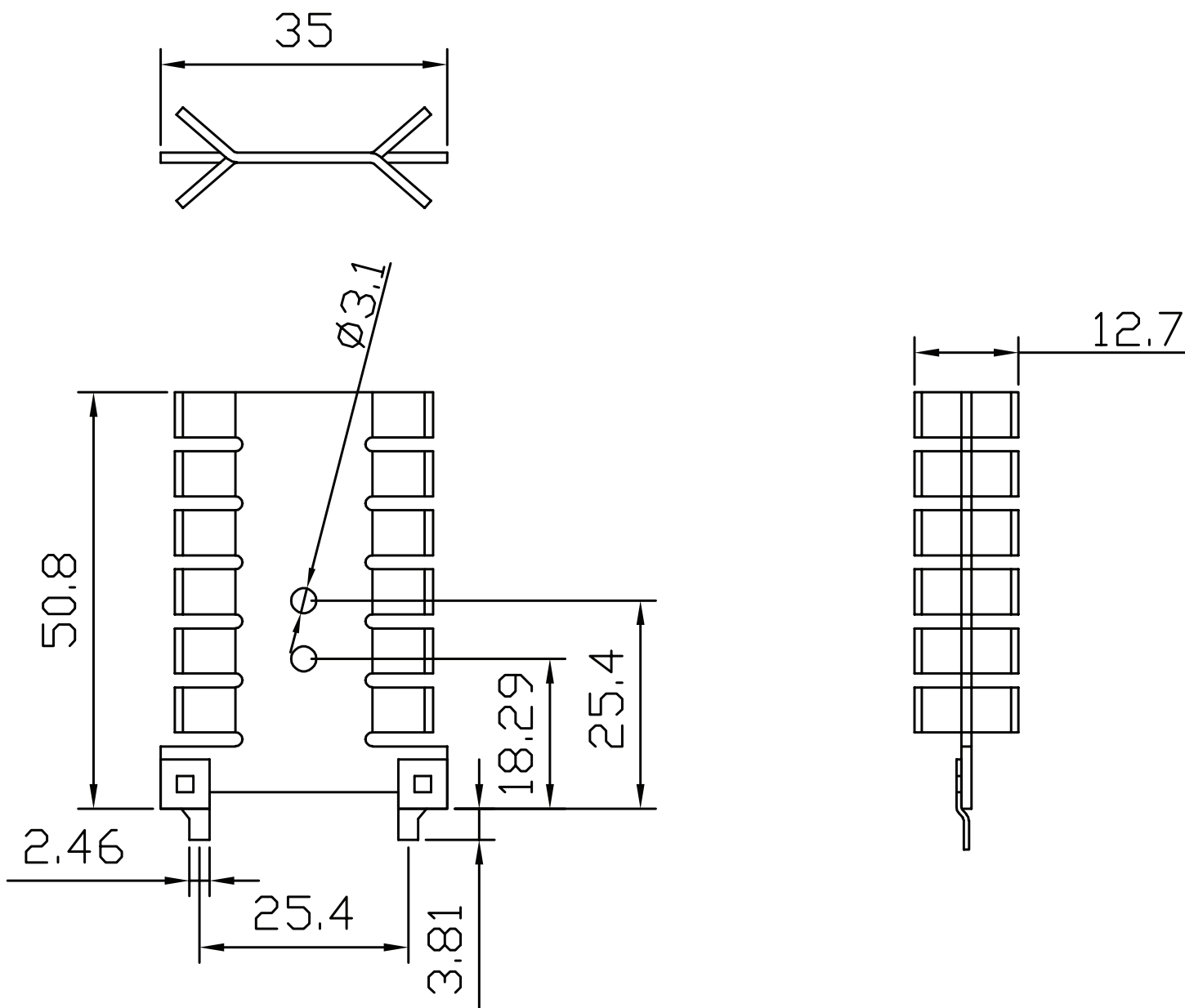


T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ±0.38 mm

MATERIAL	AL 1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	brass
PIN PLATING	2-3 μm tin
WEIGHT	5.3 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/25/2021
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



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